



## Material Content Data Sheet



Sales Product Name	SAK-TC275TP-64F200N DC			Issued		8. September 2019		
MA#	MA003843176							
Package	PG-LQFP-176-22			Weight*		1985.28 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	61.870	3.12	3.12	31164	31164
leadframe	inorganic material	phosphorus	7723-14-0	0.136	0.01		68	
	non noble metal	zinc	7440-66-6	0.543	0.03		274	
	non noble metal	iron	7439-89-6	10.869	0.55		5475	
	non noble metal	copper	7440-50-8	441.312	22.23	22.82	222291	228108
wires	noble metal	palladium	7440-05-3	0.034	0.00		17	
	non noble metal	copper	7440-50-8	3.351	0.17	0.17	1688	1705
encapsulation	organic material	carbon black	1333-86-4	4.256	0.21		2144	
	plastics	epoxy resin	-	180.180	9.08		90758	
	inorganic material	silicondioxide	60676-86-0	1234.303	62.16	71.45	621727	714629
leadfinish	noble metal	palladium	7440-05-3	0.004	0.00		2	
	noble metal	silver	7440-22-4	0.004	0.00		2	
	noble metal	gold	7440-57-5	0.007	0.00		4	
	non noble metal	nickel	7440-02-0	7.048	0.36	0.36	3550	3558
plating	noble metal	silver	7440-22-4	0.016	0.00		8	
	noble metal	palladium	7440-05-3	0.019	0.00		9	
	noble metal	gold	7440-57-5	0.030	0.00		15	
	non noble metal	nickel	7440-02-0	30.469	1.53	1.53	15348	15380
glue	plastics	epoxy resin	-	2.383	0.12		1200	
	noble metal	silver	7440-22-4	8.449	0.43	0.55	4256	5456
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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